

**CLAIM AMENDMENTS:**

Claims 1-24 (Canceled).

Claim 25 (Currently Amended): A method of manufacturing a coaxial via hole structure, comprising:

- (a) forming a first hole in a carrier;
  - (b) making the interior of the first hole conduct electricity to form an outer cylinder-shaped conductor;
  - (c) placing ~~an insulating~~ a high-dielectric-constant material in the outer cylinder-shaped conductor to form ~~an insulating fill~~ a high-dielectric-constant region;
  - (d) forming a second hole in the ~~insulating fill~~ high-dielectric-constant region, wherein the second hole has a diameter smaller than the diameter of the first hole; and
  - (e) making the interior of the second hole conduct electricity to form an inner cylinder-shaped conductor,
- wherein the coaxial via hole structure serves as a capacitor.

Claim 26 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 25, wherein in said step (b), making the interior of the first hole become conduct electricity to form an outer cylinder-shaped conductor by plating.

Claim 27 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 25, wherein in said step (e), making the interior of the second hole become conduct electricity to form an inner cylinder-shaped conductor by plating.

Claim 28 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 25, wherein in said step (e), making the interior of the second hole become conduct electricity to form an inner cylinder-shaped conductor by placing conductive paste.

Claim 29 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 25, wherein in said step (c), the insulating high-dielectric-constant material is filled in the outer cylinder-shaped conductor by plugging.

Claim 30 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 25, wherein in said step (c), the insulating high-

dielectric-constant material is filled in the outer cylinder-shaped conductor by laminating.

Claims 31-46 (Canceled):

Claim 47 (Currently Amended): A method of manufacturing a coaxial via hole structure, comprising:

(a) forming a first hole in a carrier;

(b) making the interior of the first hole become conduct electricity to form an outer cylinder-shaped conductor;

(c) placing an electrical-resistant material in the outer cylinder-shaped conductor to form an electrical-resistant fill region;

(d) forming a second hole in the electrical-resistant region, wherein the second hole has a diameter smaller than the diameter of the first hole; and

(e) making the interior of the second hole become conduct electricity to form an inner cylinder-shaped conductor,

wherein the coaxial via hole structure serves as a resistor.

Claim 48 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 47, wherein in said step (b), making the interior of the first hole become conduct electricity to form an outer cylinder-shaped conductor by plating.

Claim 49 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 47, wherein in said step (e), making the interior of the second hole become conduct electricity to form an inner cylinder-shaped conductor by plating.

Claim 50 (Currently Amended): The method of manufacturing a coaxial via hole structure as claimed in claim 47, wherein in said step (e), making the interior of the second hole become conduct electricity to form an inner cylinder-shaped conductor by placing conductive paste.

Claim 51 (New): The method of manufacturing a coaxial via hole structure as claimed in claim 47, wherein in said step (c), the electrical-resistant material is filled in the outer cylinder-shaped conductor by plugging.

Claim 52 (New): The method of manufacturing a coaxial via hole structure as claimed in claim 51, wherein in said step (c), the electrical-resistant material is filled in the outer cylinder-shaped conductor by laminating.